

Item # Tputty 504 /, Tputty 504™ Series Gap Filler Material



Tputty 504™ Series Gap Filler Material

Tputty™ 504 is a soft silicone gel thermal gap filler ideal for applications where large gap tolerances are present.

The silicone gel is filled with a complex matrix of ceramic fillers to yield superior thermal performance. Tputty™ 504 is soft and compliant transferring little to no pressure between interfaces. Because Tputty™ 504 has a higher viscosity than grease, it eliminates the bleed, separation and pump-out usually associated with grease. Bond line variances can also be more easily controlled with Tputty™ 504 than with traditional thermal pads. Tputty™ 504 can be applied like grease and is easily dispensable from a wide range of commercially available equipment including screen print, syringe and automated equipment.

SPECIFICATIONS

Construction and Composition	Ceramic-filled dispensable silicone gel
Color	Light Gray
Viscosity	6000000 to 8000000
Temperature Range	-45 to 200 °C
Outgassing TML	0.34 %
Test Method - Outgassing TML	ASTM E595
Outgassing CVCM	0.09 %
Test Method - Outgassing CVCM	ASTM E595
Thermal Conductivity	1.80 W/m-K
Test Method - Thermal Conductivity	ASTM D5470 (modified)
Thermal Impedance Final Thickness at 0.010	0.15 °C-in ² /W 0.97 °C-cm ² /W
Thermal Impedance Final Thickness at 0.020	0.27 °C-in ² /W 1.74 °C-cm ² /W
Test Method - Thermal Impedance	ASTM D5470 (modified)
Dielectric Strength	500 VAC/mil
Test Method - Dielectric Strength	ASTM D149

Volume Resistivity	$>10^{14}$ ohm-cm
Test Method - Volume Resistivity	ASTM D257
Shelf Life	Indefinite